



60V DUAL N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BVDSS	Rds(on) Max	I _D Max T _A = +25°C
	87mΩ @ V _{GS} = 10V	2.7A
60V	100mΩ @ V _{GS} = 4.5V	2.5A

Description and Applications

This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

- Backlighting
- Power Management Functions
- DC-DC Converters

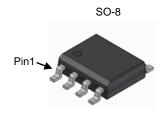
Features and Benefits

- 100% Unclamped Inductive Switch (UIS) Test in Production
- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMN6070SSDQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

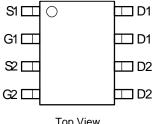
https://www.diodes.com/quality/product-definitions/

Mechanical Data

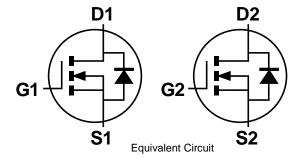
- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe Solderable per MIL-STD-202, Method 208 (§3)
- Weight: 0.074 grams (Approximate)



Top View



Top View Pin Configuration



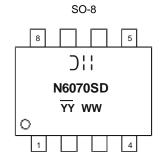
Ordering Information (Note 4)

Part Number	Case	Packaging
DMN6070SSDQ-13	SO-8	2,500/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



);; = Manufacturer's Marking
N6070SD = Product Type Marking Code
YYWW = Date Code Marking
YY = Year (ex: 20 = 2020)
WW = Week (01 to 53)



Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V_{DSS}	60	V
Gate-Source Voltage			Vgss	±20	V
Continuous Drain Current (Note 6) $V_{GS} = 10V$ Steady $T_A = +25^{\circ}C$ State $T_A = +70^{\circ}C$		I _D	2.7 2.1	А	
Maximum Continuous Body Diode Forward Current (Note 6)			Is	2.7	Α
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I _{DM}	12	Α
Avalanche Current (Note 7) L=0.1mH			las	10	Α
Avalanche Energy (Note 7) L=0.1mH			Eas	5	mJ

Thermal Characteristics (@TA= +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)		P_{D}	1.2	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	104	°C/W
Total Power Dissipation (Note 6)		PD	1.5	W
Thermal Resistance, Junction to Ambient (Note 6) Steady State		$R_{\theta JA}$	83	°C/W
Thermal Resistance, Junction to Case (Note 6)		RθJC	14.5	C/VV
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C

Electrical Characteristics (@TA= +25°C, unless otherwise specified.)

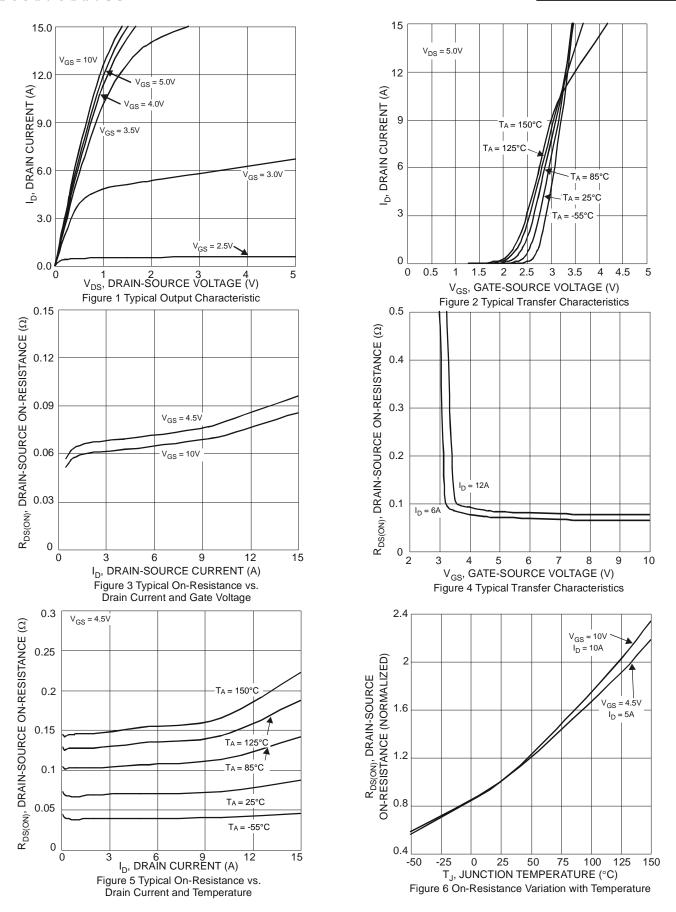
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BVDSS	60		_	V	I _D = 250µA, V _G S= 0V
Zero Gate Voltage Drain Current	IDSS	_	_	1	μA	V _{DS} = 60V, V _{GS} = 0V
Gate-Source Leakage	Igss	_	_	±100	nA	V _G S= ±16V, V _D S= 0V
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	Vgs(TH)	1.0	_	3.0	V	I _D = 250µA, V _D S= V _G S
Static Drain-Source On-Resistance	D- avanu		68	87	mΩ	VGS= 10V, ID= 4.5A
Static Dialif-Source Off-Nesistance	R _{DS(ON)}		70	100	11122	V _{GS} = 4.5V, I _D = 3.5A
Diode Forward Voltage	VsD	_	0.75	1.1	V	Is= 12A, V _G s= 0V
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	Ciss	_	588	_		V _{DS} = 30V, V _{GS} = 0V f= 1MHz
Output Capacitance	Coss	_	26.5	_	pF	
Reverse Transfer Capacitance	Crss	_	20			
Gate Resistance	Rg	_	1.5	_	Ω	VGS= 0V, VDS= 0V, f=1MHz
Total Gate Charge (V _{GS} = 4.5V)	Qg	_	5.6			
Total Gate Charge (V _{GS} = 10V)	Qg	_	12.3	_	nC	\/ 20\/ I- 2A
Gate-Source Charge	Qgs	_	1.7	_	IIC	Vps= 30V, Ip= 3A
Gate-Drain Charge	Q_{gd}	_	1.9	_		
Turn-On Delay Time	t _D (ON)	_	3.5	_		$\begin{split} V_{DD} &= 30 \text{V}, \ V_{GS} \text{=} \ 10 \text{V} \\ R_L &\cong 50 \Omega, \ R_G \cong 20 \Omega \end{split}$
Turn-On Rise Time	t _R	_	4.1	_		
Turn-Off Delay Time	t _D (OFF)	_	35	_	ns	
Turn-Off Fall Time	tF	_	11	_		
Body Diode Reverse Recovery Time	trr	_	18	_	ns	Is = 3A, dI/dt = 100A/µs
Body Diode Reverse Recovery Charge	QrR	_	12	_	nC	Is = 3A, dI/dt = 100A/µs

5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

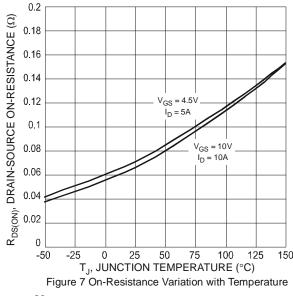
Device mounted on FR-4 substrate PC board, 2oz copper, with Thinh square copper plate.
 I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep T_J = +25°C.
 Short duration pulse test used to minimize self-heating effect.

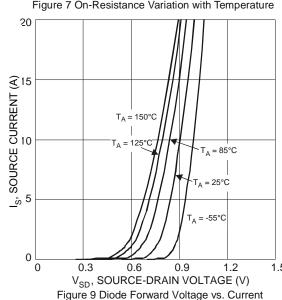
^{9.} Guaranteed by design. Not subject to product testing.

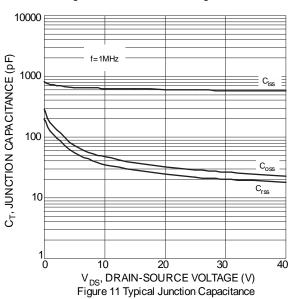












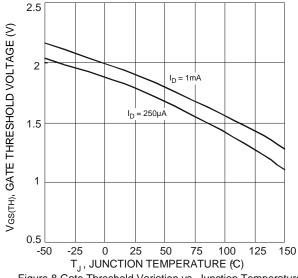
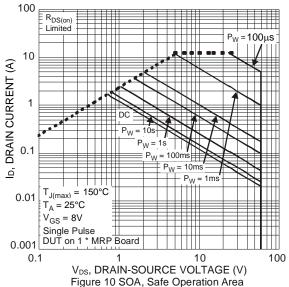


Figure 8 Gate Threshold Variation vs. Junction Temperature



10 $V_{DS} = 30V$ I_D = 3A V_{GS}, GATE-SOURCE VOLTAGE (V) 3 0k 0 4 6 8 10 Q_g, TOTAL GATE CHARGE (nC) 12 <u>1</u>4 Figure 12 Gate Charge



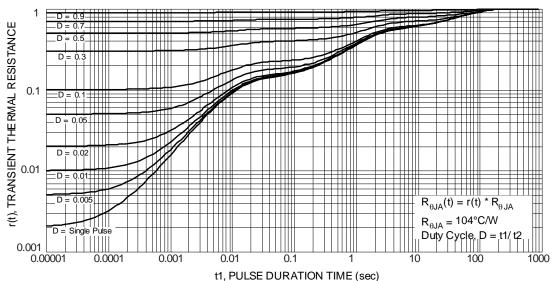


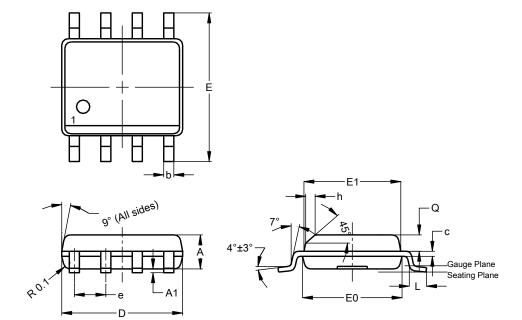
Figure 13 Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

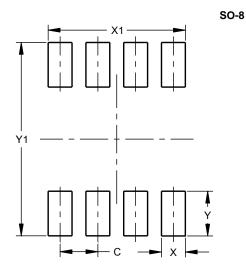
SO-8



SO-8						
Dim	Min	Max	Тур			
Α	1.40	1.50	1.45			
A1	0.10	0.20	0.15			
b	0.30	0.50	0.40			
С	0.15	0.25	0.20			
D	4.85	4.95	4.90			
Е	5.90	6.10	6.00			
E1	3.80	3.90	3.85			
E0	3.85	3.95	3.90			
е			1.27			
h			0.35			
L	0.62	0.82	0.72			
Q	0.60	0.70	0.65			
All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)			
С	1.27			
Х	0.802			
X1	4.612			
Y	1.505			
V1	6.50			



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